

# PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jing Shi</td> <td>12/15/2009</td> </tr> <tr> <td>Nyles Nettleton</td> <td>12/14/2009</td> </tr> <tr> <td>Bruce M. Guenin</td> <td>12/15/2009</td> </tr> </tbody> </table>		Name	Execution Date	Jing Shi	12/15/2009	Nyles Nettleton	12/14/2009	Bruce M. Guenin	12/15/2009		
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<b>CORRESPONDENCE DATA</b>											
<p>Fax Number: (530)759-1665  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 530-759-1663          Email: edward@parklegal.com          Correspondent Name: Edward J. Grundler          Address Line 1: Park, Vaughan &amp; Fleming, LLP          Address Line 2: 2820 Fifth Street          Address Line 4: Davis, CALIFORNIA 95618</p>											
ATTORNEY DOCKET NUMBER:	SUN10-0170										
NAME OF SUBMITTER:	Edward J. Grundler, Reg. No. 47,615										
<p>Total Attachments: 2          source=SUN10-0170_Assignment#page1.tif</p>											

OP \$40.00 12646660

**501107236**

**PATENT**  
**REEL: 024017 FRAME: 0140**



## CORPORATE ASSIGNMENT

WHEREAS, the undersigned,

Jing Shi	2270 Avenida Magnifica, Apt. P, Carlsbad, CA 92008
Nyles Nettleton	22431 Palm Avenue, Cupertino, CA 95014
Bruce M. Guenin	5013 San Joaquin Drive, San Diego, CA 92109

hereinafter termed "Inventor(s)", have invented certain new and useful improvements in

### *BASE PLATE FOR USE IN A MULTI-CHIP MODULE*

and have executed a declaration or oath for an application for a United States patent disclosing and identifying the invention:

\_\_\_ On the \_\_\_ day of \_\_\_\_\_, 20\_\_\_;

Or

X Said application having Application Number 12/646,660 and filed on 23 December 2009; and

WHEREAS, SUN MICROSYSTEMS, INC. a corporation of the State of Delaware, having a place of business at 4150 Network Circle, Santa Clara, CA 95054, (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor(s) (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor(s) to have been received in full from said Assignee:

1. Said Inventor(s) do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventor(s) hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor(s) shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use

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proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor(s) in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor(s), their respective heirs, legal representatives and assigns.

4. Said Inventor(s) hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, said Inventor(s) have executed and delivered this instrument to said Assignee as of the dates written below.

  
Jing Shi12-15-2009  
Date  
Nyles Nettleton12-14-2009  
Date  
Bruce M. Guenin12/15/2009  
Date

Date

Date